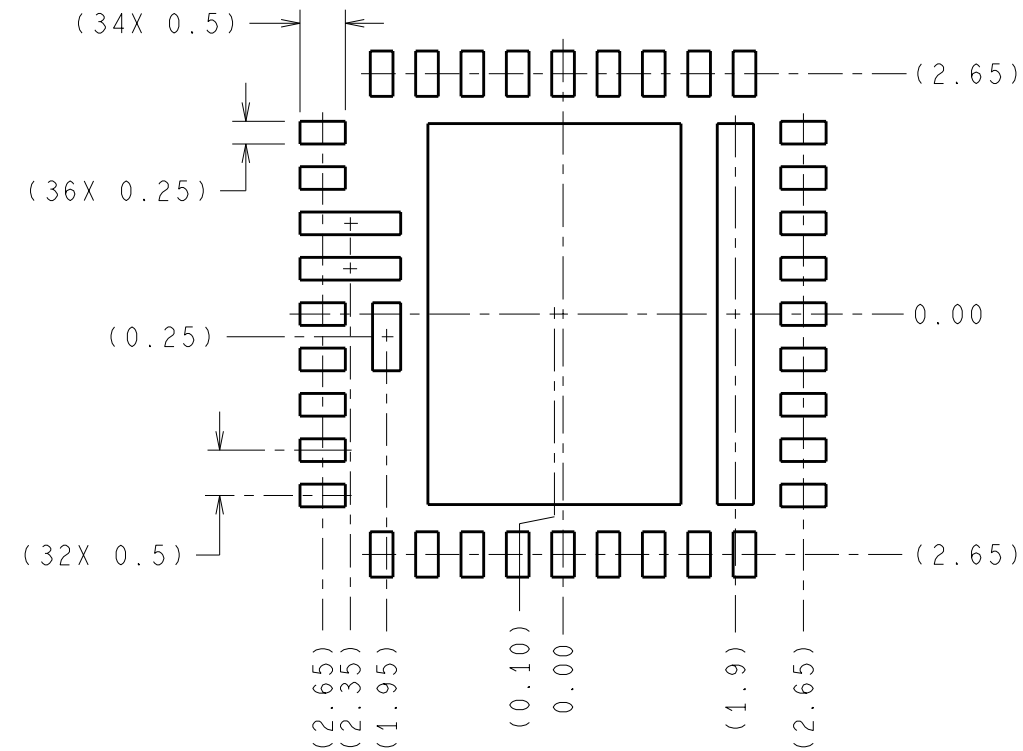
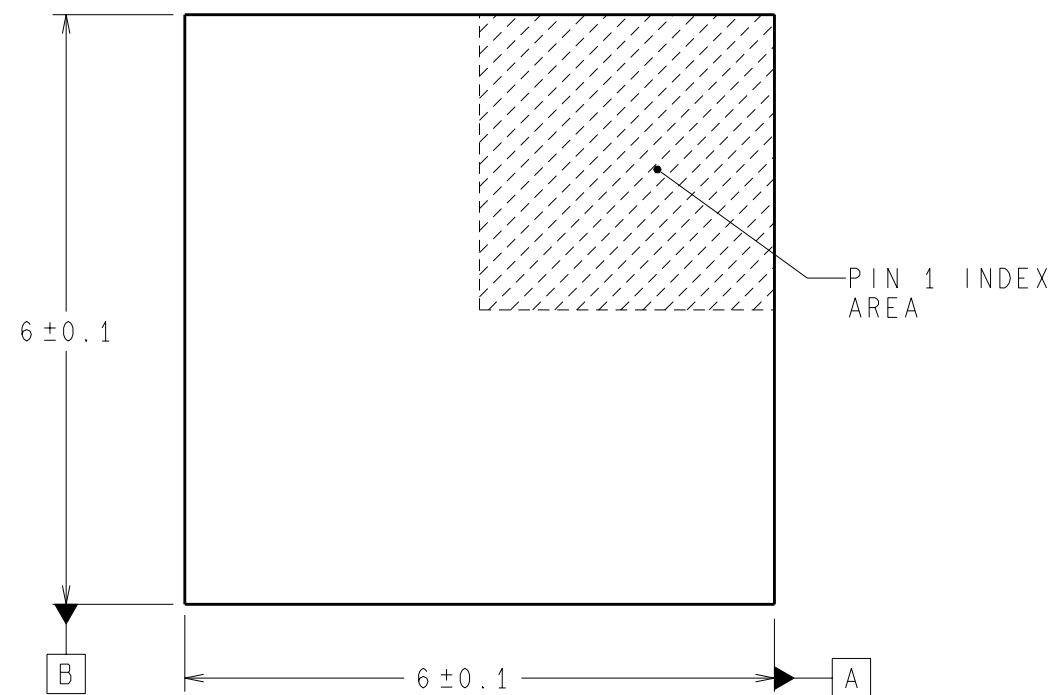


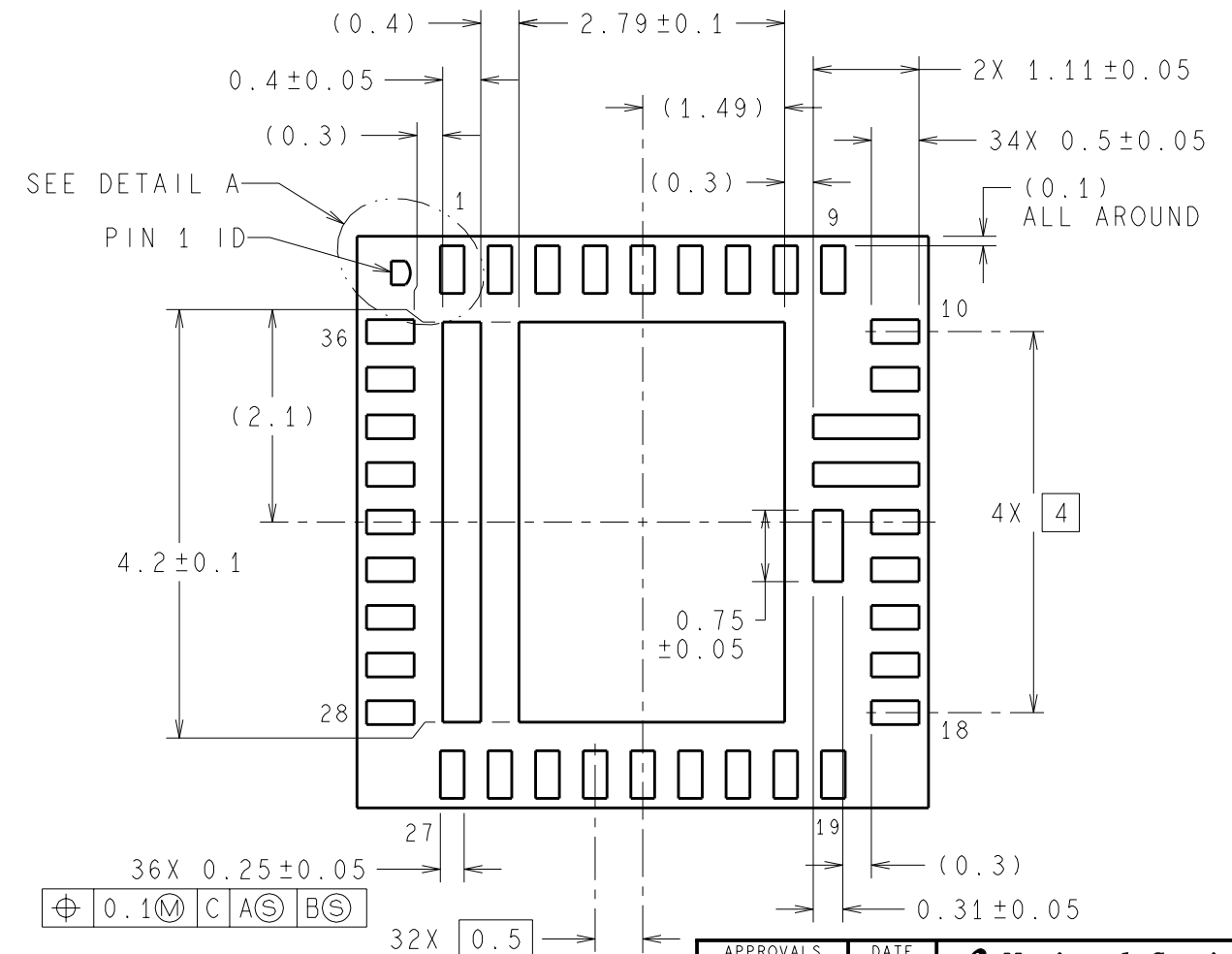
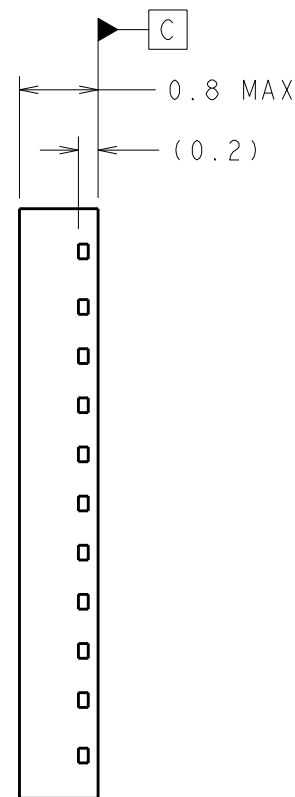
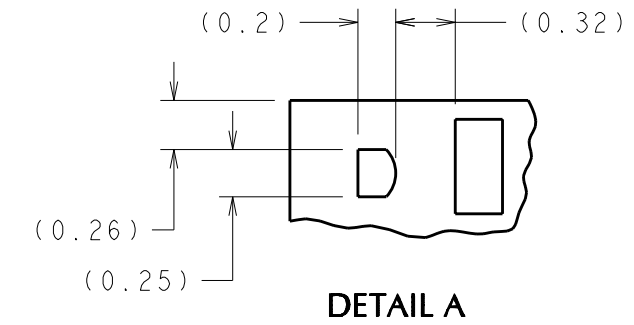
REVISIONS				
REV	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	680	04/22/2002	TL/LZ
B	REVISE PAD DESIGN; ADD DETAIL A; REVISE NOTE 1 & UPDATE NOTE 2	1105	07/21/2003	TL/VG
C	TITLE: 0.8 WAS 0.75	1185	10/17/2003	TL/VG



**RECOMMENDED LAND PATTERN**  
1:1 RATIO WITH PKG SOLDER PADS



**DIMENSIONS ARE IN MILLIMETERS**  
DIMENSIONS IN ( ) FOR REFERENCE ONLY



NOTES: UNLESS OTHERWISE SPECIFIED

- FOR SOLDER THICKNESS AND COMPOSITION, SEE "SOLDER INFORMATION" IN THE PACKAGING SECTION OF THE NATIONAL SEMICONDUCTOR WEB PAGE ([www.national.com](http://www.national.com)).
- NO JEDEC REGISTRATION AS OF OCTOBER 2003.

APPROVALS		DATE	 National Semiconductor 2900 Semiconductor Dr., Santa Clara, CA 95052-8090
DRAWN <b>T. LEQUANG</b>		04/22/2002	
DFTG. CHK. MARTA SUCHY		10/17/2003	
ENGR. CHK. VIJAYLAXMI GUMASTE		10/17/2003	
PROJECTION  MM			<b>LLP, PLASTIC, QUAD, 6 X 6 X 0.8mm BODY, 36 LD, 0.5mm PITCH, CUSTOM</b>
SCALE	SIZE	DRAWING NUMBER	REV
NTS	B	(SC)MKT-LQA36A	C
FORMERLY: N/A			SHEET 1 of 1